

Bill of Materials

TI DESIGNS

TIDA-00358

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint	Note
1	1			Printed Circuit Board	Any		Fitted	IPCB
2	1			Antenna IFFA BLE (Nothing to buy or mount)			Fitted	A1
3	2	,0402	1 uF	CAP, CERM, 1uF, 10V, +/-10% X7R, 0402	MuRata	GRM155R61A105KE15D	Fitted	C1, C15
4	5	,0402	0.1uF	CAP, CERM, 0.1uF, 10V, +/-10% X7R, 0402	MuRata	GRM155R71A104KA01D	Fitted	C2, C3, C4, C5, C7
5	1	,0402	220pF	CAP, CERM, 220pF, 50V, +/- 5%, COG/NPO, 0402	MuRata	GRM1555C1H221JA01D	Fitted	C6
6	1	,0402	2.2uF	CAP, CERM, 2.2 uF, 6.3V, +/- 20% X5R, 0402	MuRata	GRM155R60J225ME15D	Fitted	C8
7	2	,0402	1pF	CAP, CERM, 1pF, 50V, +/-, COG/NPO, 0402	MuRata	GRM1555C1H1R0CA01D	Fitted	C9, C13
8	1	,0402	0.4pF	CAP, CERM, 0.4pF, 50V, +/- 25% COG/NPO, 0402	MuRata	GRM1555C1HR40BA01D	Fitted	C10
9	2	,0402	18pF	CAP, CERM, 18pF, 50V, +/-5% COG/NPO, 0402	MuRata	GRM1555C1H180JA01D	Fitted	C11, C12
10	2	,0402	15pF	CAP, CERM, 15pF, 50V, +/- 5%, COG/NPO, 0402	MuRata	GRM1555C1H150JA01D	Fitted	C14, C16
11	2	,0402	12pF	CAP, CERM, 12pF, 50V, +/- 5%, COG/NPO, 0402	MuRata	GRM1555C1H120JA01D	Fitted	C17, C18
12	1	,0402	1000pF	CAP, CERM, 100pF, 50V, +/-5%, COG/NPO, 0402	MuRata	GRM1555C1H102JA01D	Fitted	C19
13	1	,0402	1000 ohm	0.25A Ferrite Bead, 100 ohm @ 100MHz, SMD	MuRata	BLM15HG102SN1D	Fitted	FB1
14	3	Fiducial		Fiducial Mark (there is nothing to buy or mount)	N/A	N/A	Fitted	FID1, FID2, FID3
15	4	Transparent Bumpon		Bumpon, Hemisphere, 0.44X0.20, Clear	3M	SJ-5303 (Clear)	Fitted	H9, H10, H11, H12
16	1	,0402 polarized	2.2nH	Inductor, Multilayer, Air Core, 2.2nH, 0.3A, 0.12 ohm, SMD	MuRata	LQG15HS2N2S02D	Fitted	L1
17	1	,0402 polarized	5.1nH	Inductor, Multilayer, Air Core, 5.1nH, 0.3A, 0.2 ohm, SMD	MuRata	LQG15HH5N1S02D	Fitted	L2
18	2	,0402 polarized	2nH	Inductor, Multilayer, Air Core, 2nH, 0.3A, 0.1 ohm, SMD	MuRata	LQG15HS2N0502D	Fitted	L3, L4
19	25	eg: 0603, used in PnP report		Board Edge Pad (there is nothing to buy or mount)	N/A	N/A	Fitted	PIN 1, PIN 2, PIN 3
20	1	,0201	0	RES, 0 ohm, 5%, 0.05W, 0201	Panasonic	ERJ-1GE0R00C	Fitted	R1
21	1	,0402	2.74k	RES, 2.74k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW04022K74FKED	Fitted	R16

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22	1	,0402	56.2k	RES, 56.2k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW040256K2FKED	Fitted	R17
23	1	RHA0040H		2.4 GHz- Bluetooth Low Energy and Proprietary	Texas Instruments	CC2541RHA	Fitted	U1
24	1			MC-146 32.768KHz Crystal	ingGuangHeng Electron	MC-146 32.768 KHz	Fitted	X1
25	1			Crystal, 32MHz, 10pF, SMD	n JingGuangHeng Electr	3225-4P 32M	Fitted	X2
26	0			2.5 GHz Antenna	Wonderful Hi-Tech	00-A-17B-Y-90 (2.5 GHz)	Not Fitted	A2
27	0	,0201	0	RES, 0 ohm, 5%, 0.05W, 0201	Panasonic	ERJ-1GE0R00C	Not Fitted	R2

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